

## AOS Semiconductor Product Reliability Report

AOZ8839DI-03, rev A

**Plastic Encapsulated Device** 

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This AOS product reliability report summarizes the qualification result for AOZ8839DI-03. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AOZ8839DI-03 passes AOS quality and reliability requirements. The released product will be categorized by the process family and be routine monitored for continuously improving the product quality.

## I. Reliability Stress Test Summary and Results

| Test Item                | Test Condition                                       | Time Point                | Total<br>Sample<br>Size | Number<br>of<br>Failures | Reference<br>Standard |
|--------------------------|--|---------------------------|-------------------------|--------------------------|-----------------------|
| HTRB                     | Temp = 150°C ,<br>Vdd=100% of VRWMmax                | 168 / 500 /<br>1000 hours | 462 pcs                 | 0                        | JESD22-A108           |
| Precondition<br>(Note A) | 168hr 85°C / 85%RH +<br>3 cycle reflow@260°C         | -                         | 1386 pcs                | 0                        | JESD22-A113           |
| HAST                     | 130°C , 85%RH,<br>33.3 psia,<br>Vdd = 80% of VRWMmax | 96 hours                  | 462 pcs                 | 0                        | JESD22-A110           |
| Autoclave                | 121°C , 29.7psia,<br>RH=100%                         | 96 hours                  | 462 pcs                 | 0                        | JESD22-A102           |
| Temperature<br>Cycle     | -65°C to 150°C ,<br>air to air                       | 250 / 500<br>cycles       | 462 pcs                 | 0                        | JESD22-A104           |

**Note:** The reliability data presents total of available generic data up to the published date. Note A: MSL (Moisture Sensitivity Level) 1 based on J-STD-020

## II. Reliability Evaluation

FIT rate (per billion): 7.63 MTTF = 14960 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size. Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

**Failure Rate** =  $\text{Chi}^2 \times 10^9 \text{/} [2 \text{ (N) (H) (Af)}] = 7.63 \text{MTTF} = <math>10^9 \text{/} \text{FIT} = 14960 \text{ years}$ 

Chi<sup>2</sup> = Chi Squared Distribution, determined by the number of failures and confidence interval

**N** = Total Number of units from burn-in tests

**H** = Duration of burn-in testing

Af = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

Acceleration Factor [Af] = Exp [Ea / k (1/Tj u - 1/Tj s)]

## **Acceleration Factor ratio list:**

|    | 55 deg C | 70 deg C | 85 deg C | 100 deg C | 115 deg C | 130 deg C | 150 deg C |
|----|----------|----------|----------|-----------|-----------|-----------|-----------|
| Af | 259      | 87       | 32       | 13        | 5.64      | 2.59      | 1         |

Tj s = Stressed junction temperature in degree (Kelvin), K = C+273.16

**Tj u** =The use junction temperature in degree (Kelvin), K = C+273.16

 $\mathbf{k}$  = Boltzmann's constant, 8.617164 X 10<sup>-5</sup>eV / K